

# Scott Monaghan

## List of Publications by Year in descending order

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84  
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331259

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315357

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all docs

86  
docs citations

86  
times ranked

2324  
citing authors

#	ARTICLE	IF	CITATIONS
1	Wide Spectral Photoresponse of Layered Platinum Diselenide-Based Photodiodes. Nano Letters, 2018, 18, 1794-1800.	4.5	140
2	Air sensitivity of MoS <sub>2</sub> , MoSe <sub>2</sub> , MoTe <sub>2</sub> , HfS <sub>2</sub> , and HfSe <sub>2</sub> . Journal of Applied Physics, 2016, 120, .	1.1	134
3	A systematic study of (NH <sub>4</sub> ) <sub>2</sub> S passivation (22%, 10%, 5%, or 1%) on the interface properties of the Al <sub>2</sub> O <sub>3</sub> /In <sub>0.53</sub> Ga <sub>0.47</sub> As/InP system for n-type and p-type In <sub>0.53</sub> Ga <sub>0.47</sub> As epitaxial layers. Journal of Applied Physics, 2011, 109, .	1.1	113
4	Determination of electron effective mass and electron affinity in HfO <sub>2</sub> using MOS and MOSFET structures. Solid-State Electronics, 2009, 53, 438-444.	0.8	102
5	Temperature and frequency dependent electrical characterization of HfO <sub>2</sub> /In <sub>x</sub> Ga <sub>1-x</sub> As interfaces using capacitance-voltage and conductance methods. Applied Physics Letters, 2009, 94, .	1.5	96
6	Quantum confinement-induced semimetal-to-semiconductor evolution in large-area ultra-thin PtSe <sub>2</sub> films grown at 400°C. Npj 2D Materials and Applications, 2019, 3, .	3.9	69
7	An investigation of capacitance-voltage hysteresis in metal/high-k/In <sub>0.53</sub> Ga <sub>0.47</sub> As metal-oxide-semiconductor capacitors. Journal of Applied Physics, 2013, 114, .	1.1	58
8	Electrical, structural, and chemical properties of HfO <sub>2</sub> films formed by electron beam evaporation. Journal of Applied Physics, 2008, 104, .	1.1	57
9	Impact of Forming Gas Annealing on the Performance of Surface-Channel In <sub>0.53</sub> Ga <sub>0.47</sub> As MOSFETs With an Al <sub>2</sub> O <sub>3</sub> Gate Dielectric. IEEE Transactions on Electron Devices, 2012, 59, 1084-1090.	1.6	52
10	Analysis of the minority carrier response of n-type and p-type Au/Ni/Al <sub>2</sub> O <sub>3</sub> /In <sub>0.53</sub> Ga <sub>0.47</sub> As/InP capacitors following an optimized (NH <sub>4</sub> ) <sub>2</sub> S treatment. Applied Physics Letters, 2011, 99, .	1.5	46
11	The Characterization and Passivation of Fixed Oxide Charges and Interface States in the Al <sub>2</sub> O <sub>3</sub> /InGaAs MOS System. IEEE Transactions on Device and Materials Reliability, 2013, 13, 429-443.	1.5	43
12	Structural and electrical analysis of the atomic layer deposition of HfO <sub>2</sub> /In <sub>0.53</sub> Ga <sub>0.47</sub> As capacitors with and without an Al <sub>2</sub> O <sub>3</sub> interface control layer. Applied Physics Letters, 2010, 97, .	1.5	40
13	Rhenium-doped MoS <sub>2</sub> films. Applied Physics Letters, 2017, 111, .	1.5	40
14	Charged Defect Quantification in Pt/Al <sub>2</sub> O <sub>3</sub> /In <sub>0.53</sub> Ga <sub>0.47</sub> As/InP MOS Capacitors. Journal of the Electrochemical Society, 2011, 158, G103.	1.3	33
15	Electrical analysis of three-stage passivated In <sub>0.53</sub> Ga <sub>0.47</sub> As capacitors with varying HfO <sub>2</sub> thicknesses and incorporating an Al <sub>2</sub> O <sub>3</sub> interface control layer. Journal of Vacuum Science and Technology B: Nanotechnology and Microelectronics, 2011, 29, .	0.6	31
16	TiN/ZrO <sub>2</sub> /Ti/Al Metal-Insulator-Metal Capacitors With Subnanometer CET Using ALD-Deposited ZrO <sub>2</sub> for DRAM Applications. IEEE Electron Device Letters, 2009, 30, 219-221.	2.2	26
17	Structural analysis, elemental profiling, and electrical characterization of HfO <sub>2</sub> thin films deposited on In <sub>0.53</sub> Ga <sub>0.47</sub> As surfaces by atomic layer deposition. Journal of Applied Physics, 2009, 106, 084508.	1.1	25
18	Atomic scale model interfaces between high-k hafnium silicates and silicon. Physical Review B, 2007, 75, .	1.1	24

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19	Diffusion of In <sub>0.53</sub> Ga <sub>0.47</sub> As elements through hafnium oxide during post deposition annealing. Applied Physics Letters, 2014, 104, .	1.5	23
20	Thermal decomposition mechanisms of hafnium and zirconium silicates at the atomic scale. Journal of Applied Physics, 2005, 97, 114911.	1.1	22
21	Electrically active interface defects in the In <sub>0.53</sub> Ga <sub>0.47</sub> As MOS system. Microelectronic Engineering, 2013, 109, 182-188.	1.1	22
22	Leakage current effects on C-V plots of high-k metal-oxide-semiconductor capacitors. Journal of Vacuum Science & Technology B, 2009, 27, 352.	1.3	21
23	Structural and Electrical Properties of HfO <sub>2</sub> /In <sub>x</sub> Ga <sub>1-x</sub> As structures (x: 0, 0.3, 0.5, 0.7, 1). Tj ETQq1 1 0.784314 rgBT /Over	0.3	20
24	Back-gated Nb-doped MoS <sub>2</sub> junctionless field-effect-transistors. AIP Advances, 2016, 6, .	0.6	20
25	Examining the relationship between capacitance-voltage hysteresis and accumulation frequency dispersion in InGaAs metal-oxide-semiconductor structures based on the response to post-metal annealing. Microelectronic Engineering, 2017, 178, 204-208.	1.1	20
26	Observation of peripheral charge induced low frequency capacitance-voltage behaviour in metal-oxide-semiconductor capacitors on Si and GaAs substrates. Journal of Applied Physics, 2012, 111, .	1.1	19
27	The impact of forming gas annealing on the electrical characteristics of sulfur passivated Al <sub>2</sub> O <sub>3</sub> /In <sub>0.53</sub> Ga <sub>0.47</sub> As (110) metal-oxide-semiconductor capacitors. Applied Physics Letters, 2017, 110, 142905.	1.5	19
28	Fabrication of HfO <sub>2</sub> patterns by laser interference nanolithography and selective dry etching for III-V CMOS application. Nanoscale Research Letters, 2011, 6, 400.	3.1	14
29	High aspect ratio iridescent three-dimensional metal-insulator-metal capacitors using atomic layer deposition. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2015, 33, .	0.9	14
30	Large-area growth of MoS <sub>2</sub> at temperatures compatible with integrating back-end-of-line functionality. 2D Materials, 2021, 8, 025008.	2.0	14
31	Effects of the electrical stress on the conduction characteristics of metal gate/MgO/InP stacks. Microelectronics Reliability, 2009, 49, 1052-1055.	0.9	13
32	The structural and electrical characterization of a HfErOx dielectric for MIM capacitor DRAM applications. Microelectronic Engineering, 2012, 94, 7-10.	1.1	13
33	The Role of Oxide Traps Aligned With the Semiconductor Energy Gap in MOS Systems. IEEE Transactions on Electron Devices, 2020, 67, 4372-4378.	1.6	13
34	A study of capacitance-voltage hysteresis in the HfO <sub>2</sub> /InGaAs metal-oxide-semiconductor system. Microelectronic Engineering, 2015, 147, 273-276.	1.1	12
35	Femtosecond Laser-Induced Crystallization of Amorphous Silicon Thin Films under a Thin Molybdenum Layer. ACS Applied Materials & Interfaces, 2021, 13, 37797-37808.	4.0	12
36	(Invited) Investigation of High- $\kappa$ /In <sub>x</sub> Ga <sub>1-x</sub> As Interfaces. ECS Transactions, 2010, 28, 181-190.	0.3	11

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37	Capacitance and Conductance for an MOS System in Inversion, with Oxide Capacitance and Minority Carrier Lifetime Extractions. IEEE Transactions on Electron Devices, 2014, 61, 4176-4185.	1.6	11
38	Physical, chemical and electrical characterisation of the diffusion of copper in silicon dioxide and prevention via a CuAl alloy barrier layer system. Materials Science in Semiconductor Processing, 2017, 63, 227-236.	1.9	11
39	Effects of Annealing Temperature and Ambient on Metal/PtSe <sub>2</sub> Contact Alloy Formation. ACS Omega, 2019, 4, 17487-17493.	1.6	10
40	Structural and Electrical Analysis of Thin Interface Control Layers of MgO or Al <sub>2</sub> O <sub>3</sub> Deposited by Atomic Layer Deposition and Incorporated at the High-k/III-V Interface of MO <sub>2</sub> /In <sub>x</sub> Ga <sub>1-x</sub> As (M = Hf   Zr, x = 0   0.53) Gate Stacks. ECS Transactions, 2010, 33, 69-82.	0.3	9
41	Nonhomogeneous spatial distribution of filamentary leakage current paths in circular area Pt/HfO <sub>2</sub> /Pt capacitors. Journal of Vacuum Science and Technology B: Nanotechnology and Microelectronics, 2013, 31, 01A107.	0.6	9
42	Phosphorus monolayer doping (MLD) of silicon on insulator (SOI) substrates. Beilstein Journal of Nanotechnology, 2018, 9, 2106-2113.	1.5	9
43	Electrical characterization of the soft breakdown failure mode in MgO layers. Applied Physics Letters, 2009, 95, 012901.	1.5	8
44	Degradation dynamics and breakdown of MgO gate oxides. Microelectronic Engineering, 2009, 86, 1715-1717.	1.1	8
45	(Invited) Equivalent Oxide Thickness Correction in the High-k/In <sub>0.53</sub> Ga <sub>0.47</sub> As/InP System. ECS Transactions, 2010, 33, 433-444.	0.3	8
46	Analysis of the breakdown spot spatial distribution in Pt/HfO <sub>2</sub> /Pt capacitors using nearest neighbor statistics. Journal of Applied Physics, 2013, 114, 154112.	1.1	8
47	Quantum mechanics at the core of multi-scale simulations. Journal of Computer-Aided Materials Design, 2006, 13, 89-109.	0.7	7
48	Investigation of bulk defects in amorphous and crystalline HfO <sub>2</sub> thin films. Microelectronic Engineering, 2011, 88, 1499-1502.	1.1	7
49	Exploratory study and application of the angular wavelet analysis for assessing the spatial distribution of breakdown spots in Pt/HfO <sub>2</sub> /Pt structures. Journal of Applied Physics, 2017, 122, 215304.	1.1	7
50	Soft breakdown in MgO dielectric layers. , 2009, , .		6
51	(NH <sub>4</sub> ) <sub>2</sub> S Passivation of High-k/In <sub>0.53</sub> Ga <sub>0.47</sub> As Interfaces: A Systematic Study of (NH <sub>4</sub> ) <sub>2</sub> S Concentration. ECS Transactions, 2010, 28, 231-238.	0.3	6
52	Capacitance-Voltage and Interface State Density Characteristics of GaAs and In <sub>0.53</sub> Ga <sub>0.47</sub> As MOS Capacitors Incorporating a PECVD Si <sub>3</sub> N <sub>4</sub> Dielectric. ECS Transactions, 2011, 35, 415-430.	0.3	5
53	Effects of alternating current voltage amplitude and oxide capacitance on mid-gap interface state defect density extractions in In <sub>0.53</sub> Ga <sub>0.47</sub> As capacitors. Journal of Vacuum Science and Technology B: Nanotechnology and Microelectronics, 2013, 31, 01A119.	0.6	5
54	Failure Analysis of MIM and MIS Structures Using Point-to-Event Distance and Angular Probability Distributions. IEEE Transactions on Device and Materials Reliability, 2014, 14, 1080-1090.	1.5	5

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55	Inversion in the In <sub>0.53</sub> Ga <sub>0.47</sub> As metal-oxide-semiconductor system: Impact of the In <sub>0.53</sub> Ga <sub>0.47</sub> As doping concentration. Applied Physics Letters, 2017, 110, 032902.	1.5	5
56	Effect of forming gas annealing on the inversion response and minority carrier generation lifetime of n and p-In <sub>0.53</sub> Ga <sub>0.47</sub> As MOS capacitors. Microelectronic Engineering, 2015, 147, 325-329.	1.1	4
57	Spatial analysis of failure sites in large area MIM capacitors using wavelets. Microelectronic Engineering, 2017, 178, 10-16.	1.1	4
58	Assessing the Correlation Between Location and Size of Catastrophic Breakdown Events in High-K MIM Capacitors. IEEE Transactions on Device and Materials Reliability, 2019, 19, 452-460.	1.5	4
59	Investigating interface states and oxide traps in the MoS <sub>2</sub> /oxide/Si system. Solid-State Electronics, 2021, 186, 108123.	0.8	4
60	Effects of the Semiconductor Substrate Material on the Post-breakdown Current of MgO Dielectric Layers. ECS Transactions, 2009, 25, 79-86.	0.3	3
61	Multi-technique characterisation of MOVPE-grown GaAs on Si. Microelectronic Engineering, 2011, 88, 472-475.	1.1	3
62	Structural and optical properties of post-annealed atomic-layer-deposited HfO <sub>2</sub> thin films on GaAs. Thin Solid Films, 2014, 569, 104-112.	0.8	3
63	Characterization of the Failure Site Distribution in MIM Devices Using Zoomed Wavelet Analysis. Journal of Electronic Materials, 2018, 47, 5033-5038.	1.0	3
64	Detection of inhibitory effects in the generation of breakdown spots in HfO <sub>2</sub> -based MIM devices. Microelectronic Engineering, 2019, 215, 111023.	1.1	3
65	Stress in silicon interlayers at the SiO <sub>2</sub> /Ge interface. Applied Physics Letters, 2007, 90, 143511.	1.5	2
66	Determination of physical parameters for HfO <sub>2</sub> /SiO <sub>x</sub> /TiN MOSFET gate stacks by electrical characterization and reverse modeling. , 2008, , .		2
67	Electrical characterisation of InGaAs on insulator structures. Microelectronic Engineering, 2015, 147, 63-66.	1.1	2
68	Hall-effect mobility for a selection of natural and synthetic 2D semiconductor crystals. , 2017, , .		2
69	Post-breakdown conduction in metal gate/MgO/InP structures. , 2009, , .		1
70	Scalable high-k metal-insulator-metal capacitors with low leakage, high breakdown fields and improved voltage linearity. Electronics Letters, 2012, 48, 230.	0.5	1
71	(Invited) Can Metal/Al <sub>2</sub> O <sub>3</sub> /In <sub>0.53</sub> Ga <sub>0.47</sub> As/InP MOSCAP Properties Translate to Metal/Al <sub>2</sub> O <sub>3</sub> /In <sub>0.53</sub> Ga <sub>0.47</sub> As/InP MOSFET Characteristics. ECS Transactions, 2012, 45, 79-88.	0.3	1
72	Study of interface and oxide defects in high-k/In<sub>0.53</sub>/Ga<sub>0.47</sub>/n-MOSFETs. , 2012, , .		1

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73	Spatial statistics for micro/nanoelectronics and materials science. , 2012, , .		1
74	Relationship between capacitance and conductance in MOS capacitors. , 2019, , .		1
75	Electrical Properties of LaLuO <sub>3</sub> /Si(100) Structures Prepared by Molecular Beam Deposition. ECS Transactions, 2010, 33, 221-227.	0.3	0
76	Transport and interface states in high- $\hat{\nu}$ LaSiO <sub>x</sub> dielectric. Microelectronic Engineering, 2011, 88, 1342-1345.	1.1	0
77	Electrical Properties of High- $\kappa$ LaLuO <sub>3</sub> Gate Oxide for SOI MOSFETs. Advanced Materials Research, 0, 276, 87-93.	0.3	0
78	Electrical Properties and Charge Transport in the Pd/Al <sub>2</sub> O <sub>3</sub> /InGaAs MOS Structure. ECS Transactions, 2013, 58, 379-384.	0.3	0
79	Charge Trapping Characterization of LaLuO <sub>3</sub> /p-Si Interfaces at Cryogenic Temperatures. ECS Transactions, 2014, 61, 55-59.	0.3	0
80	On the interpretation of MOS impedance data in both series and parallel circuit topologies. Solid-State Electronics, 2021, 185, 108098.	0.8	0
81	Application of artificial neural networks to the identification of weak electrical regions in large area MIM structures. Microelectronics Reliability, 2021, , 114312.	0.9	0
82	Failure Analysis of Large Area Pt/HfO <sub>2</sub> /Pt Capacitors Using Multilayer Perceptrons. , 2021, , .		0
83	Chemical Vapor Deposition of MoS <sub>2</sub> for Back-End-of-Line Applications. ECS Meeting Abstracts, 2021, MA2021-02, 1952-1952.	0.0	0
84	(Invited) Investigating Defects in the High- $\kappa$ /Ingaas System at Cryogenic Temperature. ECS Meeting Abstracts, 2022, MA2022-01, 1056-1056.	0.0	0